

Bill of Materials

TI DESIGNS

TIDA-00267 - Polarity Correcting Isolated CAN Node

Item	Quantity	Reference	Part	Footprint	Manufacturer	Manufacturer Part Number	Notes
1	3	C1,C4,C6	1µF	805	Any	Any	
2	2	C2,C3	.1μF	805	Any	Any	
3	1	C5	4.7µF	805	Any	Any	
4	4	C7,C8,C12,C14	0.1μ	805	Any	Any	
5	2	C9,C15	82pF	805	Any	Any	
6	2	C10,C11	1nF	805	Any	Any	
7	1	C13	4.7nF	805	Any	Any	
8	2	D1,D2	MBR0520L	SOD123	On-Semiconductor	MBR0520LT1G	
9	2	D3,D4	TVS	SC-70	On-Semiconductor	MMBZ27VAWT1G	Use either D3 & D4 or D5
10	1	D5	NUP2105	SOT_3DBZ	On-Semiconductor	NUP2105LT1G	Use either D3 & D4 or D5
11	2	JMP1,JMP2	Header 1x4	HDR_THVT_1X4_100	Any	Any	
12	1	L1	CHOKE CM14	SMD Choke	EPCOS	B82789C0104N002	
13	2	R1,R5	4.7k	805	Any	Any	
14	2	R2,R6	0	805	Any	Any	
15	2	R3,R7	60	805	Any	Any	
16	1	R4	120	805	Any	Any	
17	1	TB1	Terminal Block 1x2	TB_THRTSCR_1x2_100	Any	Any	
18	1	T1	T_Wurth_7603900xx	CoilCraft_DA23xx_AL	Wurth Electronics	760390015	
19	1	U1	SN6501	SOT_5DBV	Texas Instruments	SN6501DBV	
20	1	U2	TPS76350	SOT_5DBV	Texas Instruments	TPS76350DBV	
21	2	U3,U7	SN65HVD255	SOIC_8D	Texas Instruments	SN65HVD255D	·
22	1	U4	ISO7842	SOIC_16DW	Texas Instruments	ISO7842DW	
23	1	U5	TPS22968	DPU	Texas Instruments	TPS22968DPU	
24	1	U6	SN74AHCT1G04	SOT_5DBV	Texas Instruments	SN74AHCT1G04DBV	

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